

アルマイト層を利用した高熱伝導性プリント配線板

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High Thermal Conductivity Printed Circuit Boards Using Anodized Aluminum Layer

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Abstract

The high performance of electronic devices, such as personal computers and cellular phones, has led to an increase in the heat generated by their electronic parts. In printed circuit boards (PCBs) with many electronic parts we encounter higher heat radiation than ever before, and at the same time we require higher reliability. At present, high thermal conductivity PCBs with metal and ceramics substrates are used. In this study, we were attracted to anodized aluminum film for its non-conductivity and high thermal conductivity properties. By using the anodized aluminum film as an insulating layer, we succeeded in making a PCB with excellent non-conductivity and high thermal conductivity.

Key Words: *High Thermal Conductivity PCBs, Anodized Aluminum Treatment, Re-anodic Oxide Coating Treatment*